

TLP7830

1. Applications

- Motor phase and rail current sensing
- Power inverter current and voltage sensing

2. General

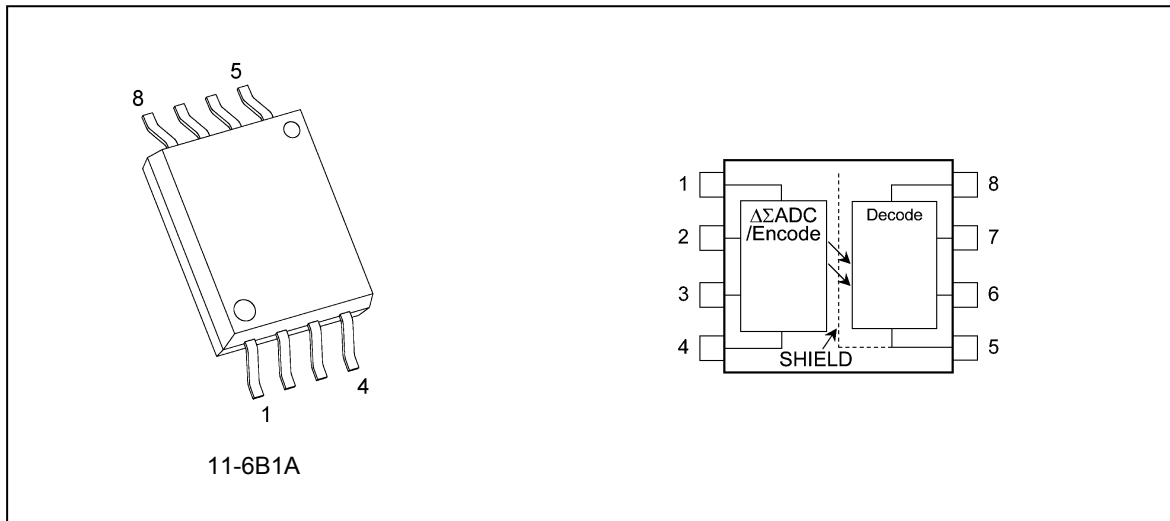
The TLP7830 is a 1-bit, second-order sigma-delta ($\Sigma\text{-}\Delta$) modulator converts an analog input signal into a high-speed data stream with galvanic isolation based on optical coupling technology.

3. Features

- (1) Output clock frequency: 10 MHz (typ.)
- (2) 16 bits resolution no missing codes [ENOB:12 bits(typ.)]
- (3) Integral non-linearity: 4 LSB (typ.)
- (4) Input offset voltage: 0.6 mV (typ.)
- (5) Operating temperature range: -40 to 105 °C
- (6) Common-mode transient immunity: 15 kV/ μ s (min)
- (7) Safety standards
 - UL-approved: UL1577, File No.E67349
 - cUL-approved: CSA Component Acceptance Service No.5A File No.E67349
 - VDE-approved: EN60747-5-5, EN60065 or EN60950-1 (**Note 1**)

Note 1: When a VDE approved type is needed, please designate the **Option (D4)**.

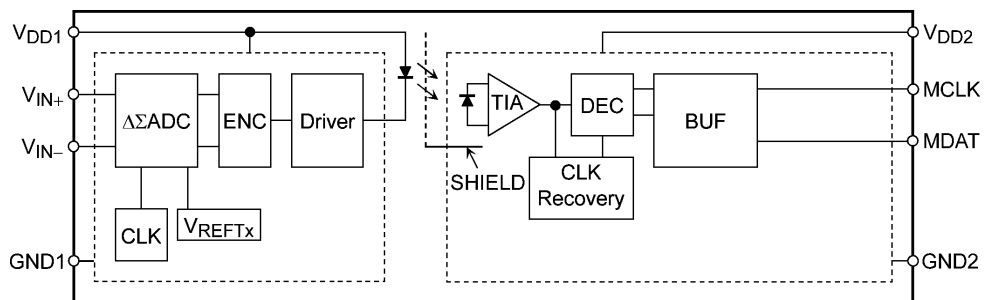
4. Packaging and Pin Assignment



4.1. Pin Assignment

Pin No.	Symbol	Description
1	V _{DD1}	Input side supply voltage
2	V _{IN+}	Positive input
3	V _{IN-}	Negative input
4	GND1	Input side ground
5	GND2	Output side ground
6	MDAT	Modulator data output
7	MCLK	Modulator clock output
8	V _{DD2}	Output side supply voltage

5. Internal Circuit (Note)



Note: A 0.1- μ F bypass capacitor must be connected between 1 and 4 pins and between 5 and 8 pins.

6. Principle of Operation

6.1. Mechanical Parameters

Characteristics	SO8L	Unit
Height	2.3 (Max)	mm
Creepage distances	8.0 (Min)	
Clearance	8.0 (Min)	
Internal isolation thickness	0.4 (Min)	

7. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Rating	Unit
Supply Voltages	V _{DD1} , V _{DD2}		-0.5 to 6	V
Steady-state input voltages	V _{IN+} , V _{IN-}		-0.5 to V _{DD1} + 0.5	
Two-second transient input voltages	V _{IN+} , V _{IN-}		-6 to V _{DD1} + 0.5	
Input power dissipation	P _D	(Note 1)	72	mW
Digital output voltage	MCLK, MDAT		-0.5 to 6	V
Output power dissipation	P _O	(Note 1)	48	mW
Operating temperature	T _{opr}		-40 to 105	°C
Storage temperature	T _{stg}		-55 to 125	
Lead soldering temperature (10 s)	T _{sol}	(Note 2)	260	
Isolation voltage AC, 60 s, R.H. ≤ 60 %	BV _S	(Note 3)	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note: Ceramic capacitors (0.1 μF) should be connected between 1 and 4 pins and between 5 and 8 pins to stabilize the operation. Otherwise, this photocoupler may not switch properly. The bypass capacitors should be placed as close as possible to each pin.

Note 1: Input power dissipation derating (T_a ≥ 110.6 °C): -5.0 mW/°C
 Output power dissipation derating (T_a ≥ 115.4 °C): -5.0 mW/°C

Note 2: ≥ 2 mm below seating plane.

Note 3: This device is considered as a two-terminal device: Pins 1, 2, 3 and 4 are shorted together, and pins 5, 6, 7 and 8 are shorted together.

8. Recommended Operating Conditions (Note)

Characteristics	Symbol	Note	Min	Typ.	Max	Unit
Input side supply voltage	V _{DD1}		4.5	5	5.5	V
Output side supply voltage	V _{DD2}		3	—	5.5	
Analog input voltage	V _{IN+} , V _{IN-}	(Note 1), (Note 2)	-200	—	200	mV
Ambient temperature	T _a		-40	—	105	°C

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this datasheet should also be considered.

Note 1: FSR = ±320 mV

Note 2: When either V_{IN+} or V_{IN-} or both are equal to or greater than V_{DD1} - 2 V (e.g., if V_{DD1} = 5 V, when V_{IN+} and/or V_{IN-} are equal to or greater than 5 V - 2 V = 3 V), isolation amplifiers go into one of the test modes. Do not raise either V_{IN+} or V_{IN-} above this voltage to keep the device in functional mode.

9. Electrical Characteristics

9.1. DC Characteristics (Note) (Unless otherwise specified, $T_a = -40$ to 105 °C, $V_{DD1} = 4.5$ to 5.5 V, $V_{DD2} = 3$ to 5.5 V, $V_{IN+} = -200$ to 200 mV, $V_{IN-} = 0$ V)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Integral non-linearity	INL	$T_a = -40$ to 85 °C	-15	4	15	LSB
		$T_a = 105$ °C	-25	4	25	
Differential non-linearity	DNL		-0.9	0.5	0.9	LSB
Input offset voltage	V_{OS}		-1.0	0.6	2.0	mV
Input offset voltage drift vs ambient temperature	$ dV_{OS}/dT_a $		—	1.2	3	$\mu\text{V}/^\circ\text{C}$
Input offset voltage drift vs input side supply voltage	$ dV_{OS}/dV_{DD1} $		—	150	—	$\mu\text{V}/\text{V}$
Internal Reference Voltage	V_{REF}		—	320	—	mV
Gain error	G_E	$T_a = 25$ °C	-1	0.1	1	%
Gain error	G_E	$T_a = -40$ to 105 °C	-2	0.1	2	%
Input common-mode rejection ratio	$CMRR_{IN}$		—	74	—	dB
Signal-to-noise ratio	SNR	$V_{IN+} = 400$ mV _{p-p} , 1 kHz sine wave	68	80	—	dB
Signal-to-(noise + distortion) Ratio	SNDR		65	75	—	dB
Effective number of bits	ENOB		—	12	—	bits
Total harmonic distortion	THD		—	-78	—	dB
Input side supply current (V_{DD1})	I_{DD1}	$V_{IN+} = 0$ V	—	8.5	12	mA
Output side supply current (V_{DD2})	I_{DD2}	$V_{IN+} = 0$ V, $V_{DD2} = 3.3$ V	—	4.6	7	mA
	I_{DD2}	$V_{IN+} = 0$ V, $V_{DD2} = 5$ V	—	4.9	8	mA
Low-level output voltage	V_{OL}	$I_{OUT} = 200$ μA	—	0.03	0.05	V
High-level output voltage	V_{OH}	$I_{OUT} = -200$ μA , $V_{DD2} = 3.3$ V	3.1	3.2	—	V
	V_{OH}	$I_{OUT} = -200$ μA , $V_{DD2} = 5$ V	4.8	4.9	—	V
Output short-circuit current	I_{OSC}		—	11	—	mA
Equivalent input resistance	R_{IN}		—	80	—	k Ω

Note: Tested with a Sinc³ filter with a decimation ratio of 256 (with the decimation filter output configured to 16 bits).

Note: All typical values are at $V_{DD1} = 5$ V, $V_{DD2} = 5$ V, $T_a = 25$ °C, unless otherwise noted.

10. AC Characteristics (Note) (Unless otherwise specified, $T_a = -40$ to 105 °C, $V_{DD1} = 4.5$ to 5.5 V, $V_{DD2} = 3$ to 5.5 V)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Output clock frequency	f_{CLK}		8.5	10	11.5	MHz
Access time after MCLK rising edge	t_a	$C_L = 15$ pF	—	33	45	ns
Hold time after MCLK rising edge	t_h		10	24	—	
Common-mode transient immunity	CMTI	$V_{CM} = 1$ kV, $T_a = 25$ °C	15	20	—	kV/ μ s

Note: All typical values are at $T_a = 25$ °C.

C_L is approximately 15 pF which includes probe and stray wiring capacitance.

11. Isolation Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Total capacitance (input to output)	C_S	(Note 1)	$V_S = 0$ V, $f = 1$ MHz	—	1.0	—	pF
Isolation resistance	R_S	(Note 1)	$V_S = 500$ V, R.H. ≤ 60 %	1×10^{12}	10^{14}	—	Ω
Isolation voltage	BV_S	(Note 1)	AC, 60 s	5000	—	—	Vrms
			AC, 1 s in oil	—	10000	—	
			DC, 60 s in oil	—	10000	—	Vdc

Note 1: This device is considered as a two-terminal device: Pins 1, 2, 3 and 4 are shorted together, and pins 5, 6, 7 and 8 are shorted together.

12. Characteristics Curves (Note)

$V_{IN-} = 0$ V. Tested with a Sinc³ filter with a decimation ratio of 256 (with the decimation filter output configured to 16 bits)

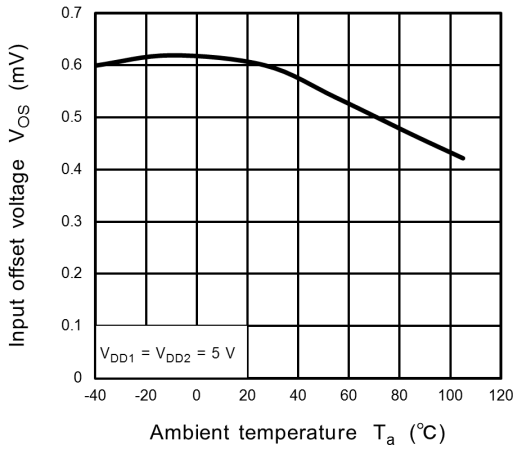


Fig. 12.1 $V_{OS} - T_a$

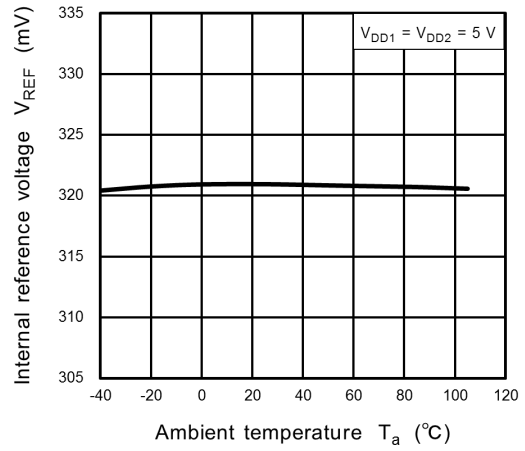


Fig. 12.2 $V_{REF} - T_a$

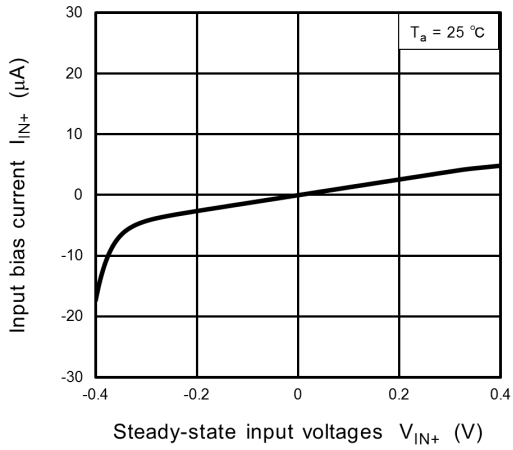


Fig. 12.3 $V_{IN+} - I_{IN+}$

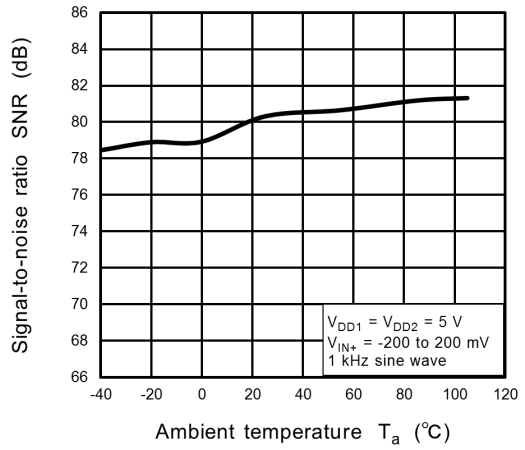


Fig. 12.4 $SNR - T_a$

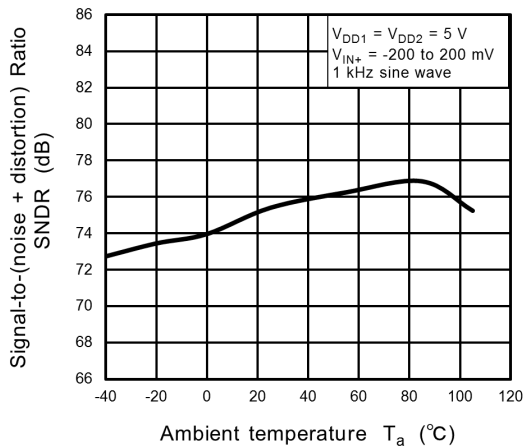


Fig. 12.5 $SNDR - T_a$

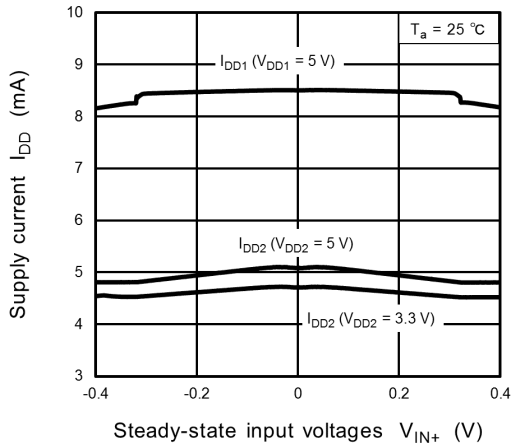


Fig. 12.6 $I_{DD} - V_{IN+}$

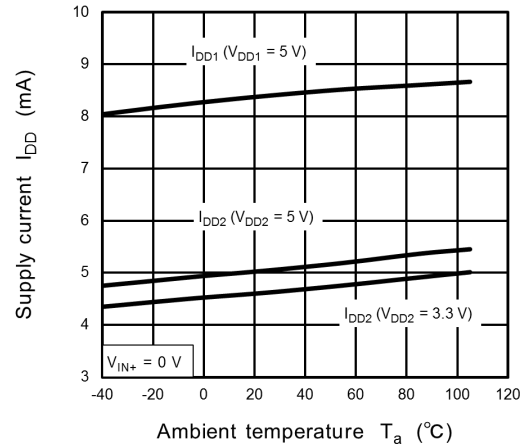


Fig. 12.7 $I_{DD} - T_a$

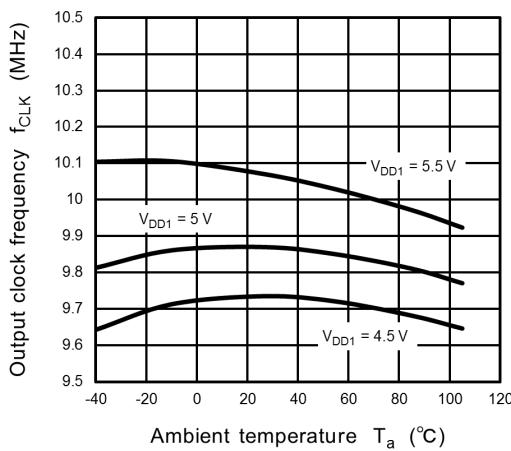


Fig. 12.8 $f_{CLK} - T_a$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

13. Soldering and Storage

13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

- When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.

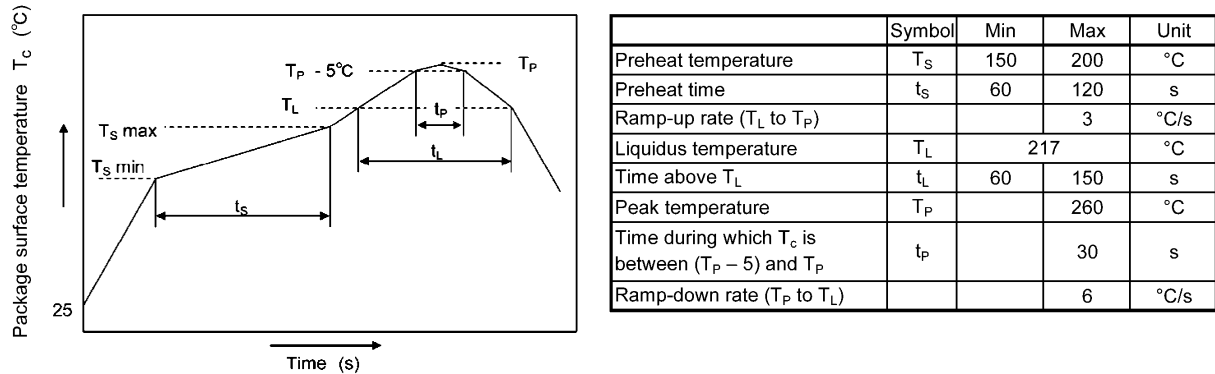


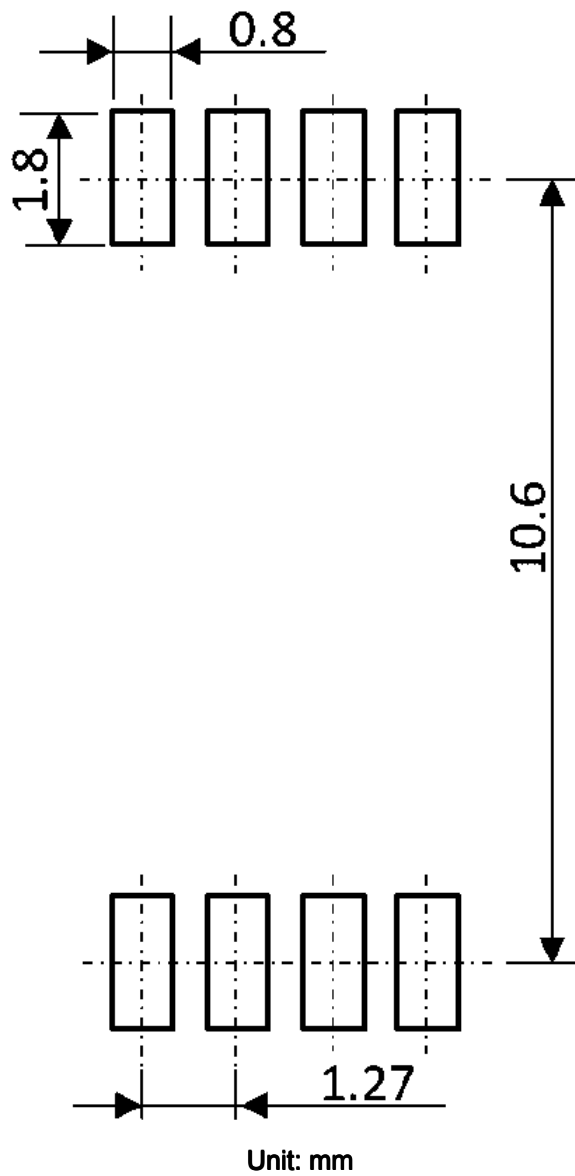
Fig. 13.1.1 An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

- When using soldering flow
Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.
Mounting condition of 260 °C within 10 seconds is recommended.
Flow soldering must be performed once.
- When using soldering Iron
Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C
Heating by soldering iron must be done only once per lead.

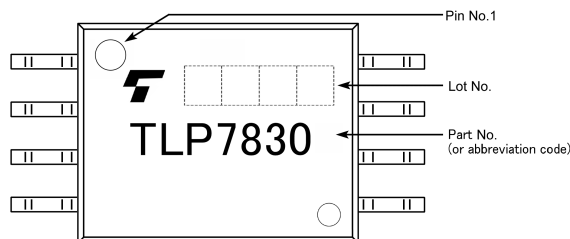
13.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

14. Land Pattern Dimensions (for reference only)



15. Marking



16. EN60747-5-5 Option (D4) Specification

- Part number: TLP7830 (**Note 1**)
- The following part naming conventions are used for the devices that have been qualified according to option (D4) of EN60747.

Example: TLP7830(D4-TL,E(O

D4: EN60747 option

TL: Tape type

E: [[G]]/RoHS COMPATIBLE (**Note 2**)

O: Domestic ID (Country / Region of origin: Japan)

Note 1: Use TOSHIBA standard type number for safety standard application.

e.g., TLP7830(D4-TL,E(O → TLP7830

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

Description	Symbol	Rating	Unit
Application classification for rated mains voltage ≤ 150 Vrms for rated mains voltage ≤ 300 Vrms		I-IV I-III	—
Climatic classification		55 / 125 / 21	—
Pollution degree		2	—
Maximum operating insulation voltage	V _{IORM}	1230	V _{peak}
Input to output test voltage, Method A V _{pr} = 1.6 × V _{IORM} , type and sample test t _p = 10 s, partial discharge < 5 pC	V _{pr}	1970	V _{peak}
Input to output test voltage, Method B V _{pr} = 1.875 × V _{IORM} , 100 % production test t _p = 1 s, partial discharge < 5 pC	V _{pr}	2310	V _{peak}
Highest permissible overvoltage (transient overvoltage, t _{pr} = 60 s)	V _{TR}	8000	V _{peak}
Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve) current (input current I _F , P _{SO} = 0) power (output or total power dissipation) temperature	I _{si} P _{so} T _s	250 400 150	mA mW °C
Insulation resistance V _{IO} = 500 V, T _a = 25 °C V _{IO} = 500 V, T _a = 100 °C V _{IO} = 500 V, T _a = T _s	R _{si}	≥ 10 ¹² ≥ 10 ¹¹ ≥ 10 ⁹	Ω

Fig. 16.1 EN60747 Insulation Characteristics

Minimum creepage distance	Cr	8.0 mm
Minimum clearance	Cl	8.0 mm
Minimum insulation thickness	ti	0.4 mm
Comparative tracking index	CTI	175

Fig. 16.2 Insulation Related Specifications (Note)

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.



Fig. 16.3 Marking on Packing for EN60747

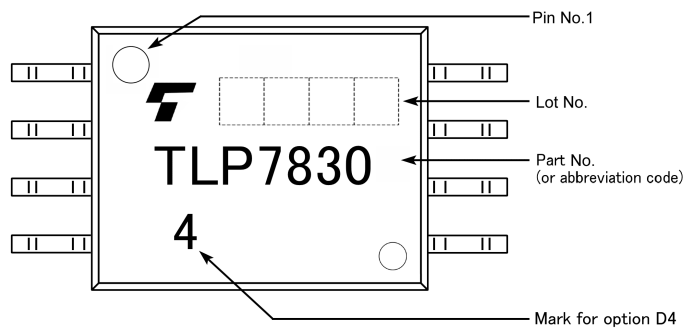


Fig. 16.4 Marking Example (Note)

Note: The above marking is applied to the photocouplers that have been qualified according to option (D4) of EN60747.

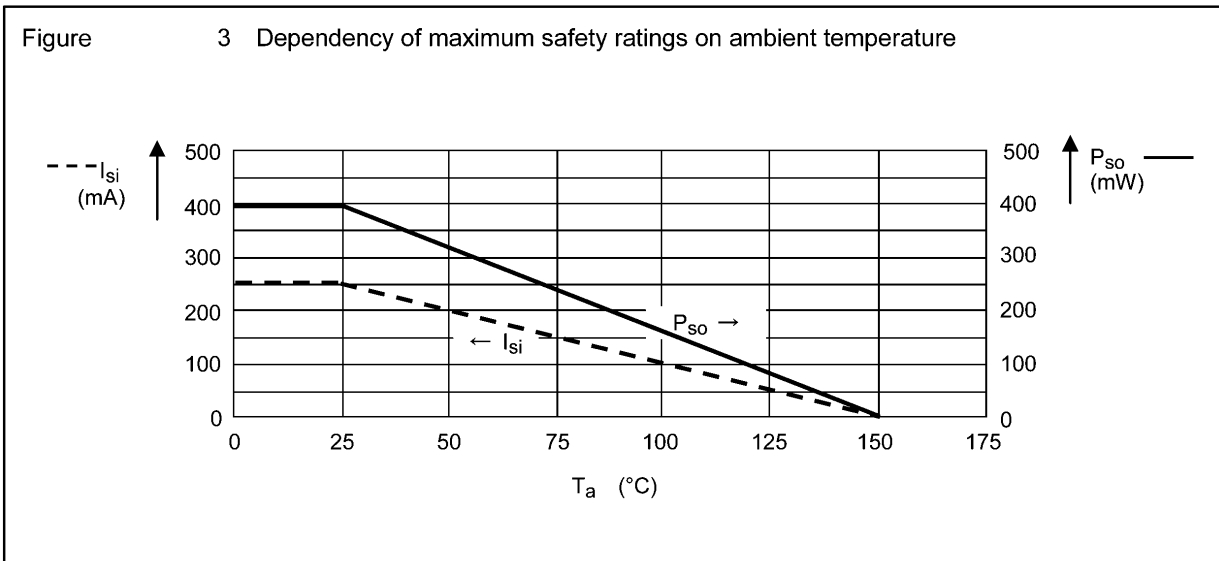
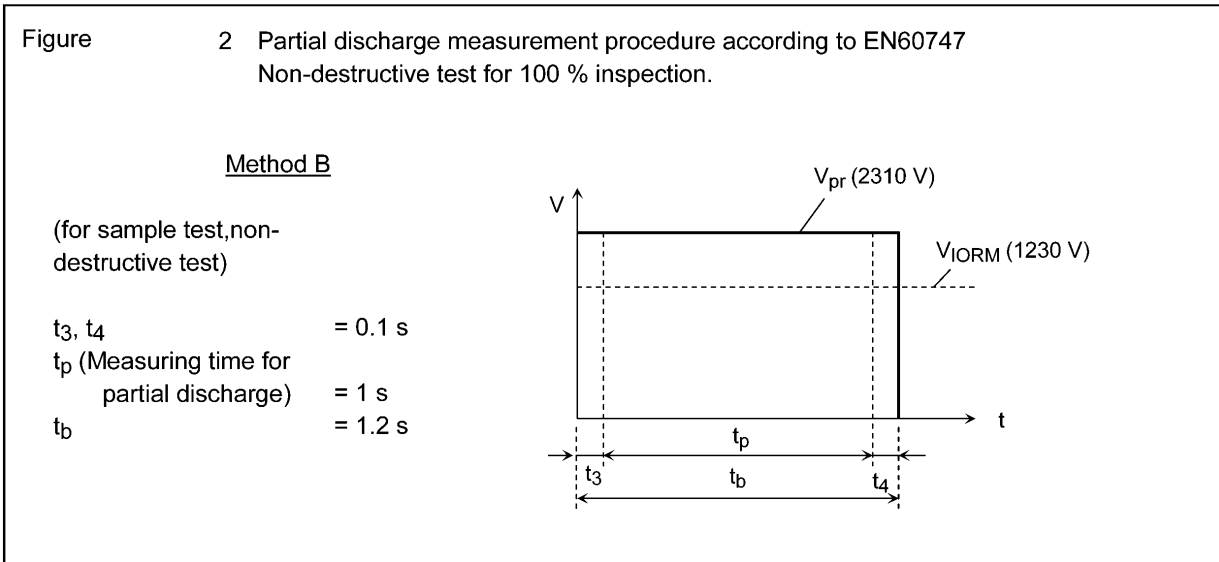
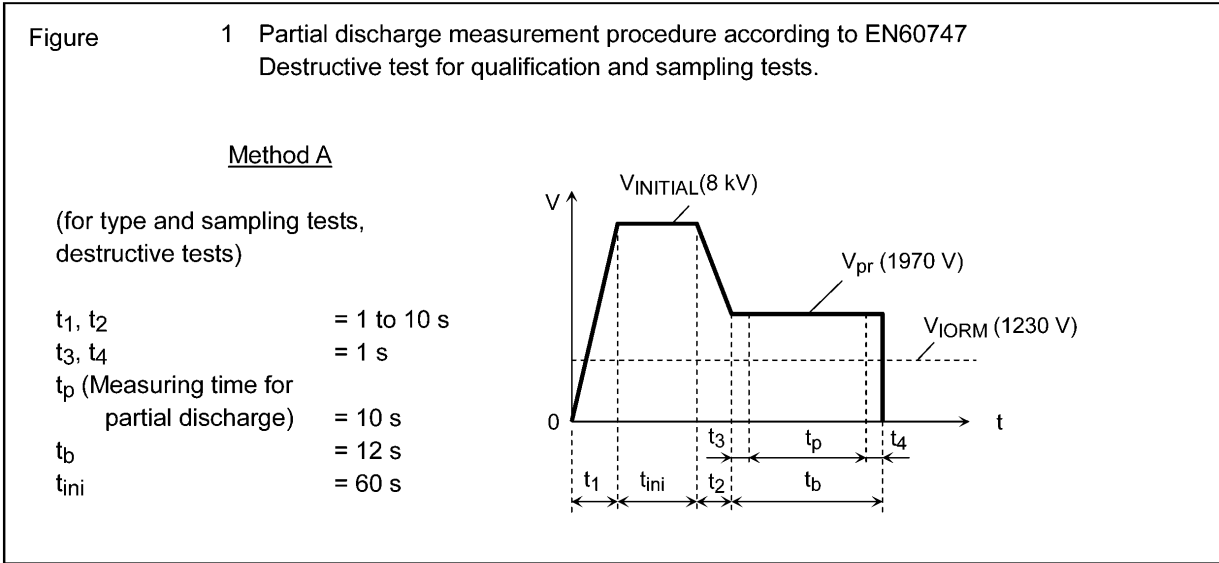


Fig. 16.5 Measurement Procedure

17. Embossed-Tape Packing (TL) Specification for Mini-Flat Photocouplers

17.1. Applicable Package

Package Name	Product Type
SO8L	Long creepage mini flat coupler

17.2. Product Naming Conventions

Type of package used for shipment is denoted by a symbol suffix after a part number. The method of classification is as below.

Example) TLP7830(TL,E(O)

Part number: TLP7830

Tape type: TL

[[G]]/RoHS COMPATIBLE: E (**Note 1**)

Domestic ID (Country / Region of origin: Japan): O

Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

17.3. Tape Dimensions Specification

Tape Type	Packing Amount (A unit per reel)
TL	1500

17.3.1. Orientation of Device in Relation to Direction of Feed

Device orientation in the carrier cavities as shown in the following figure.

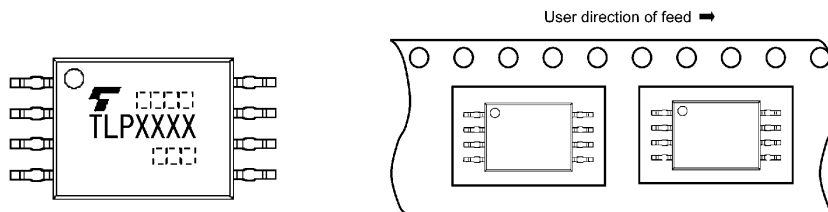


Fig. 17.3.1.1 Device Orientation

17.3.2. Empty Cavities

Characteristics	Criterion	Remarks
Occurrences of 2 or more successive empty cavities	0 device	Within any given 40-mm section of tape, not including leader and trailer
Single empty cavity	6 devices (max) per reel	Not including leader and trailer

17.3.3. Tape Leader and Trailer

The start end of the tape has 50 or more empty cavities. The hub end of the tape has 50 or more empty cavities and two empty turns only for a cover tape.

17.3.4. Tape Dimensions

Tape material: Plastic (for protection against static electricity)

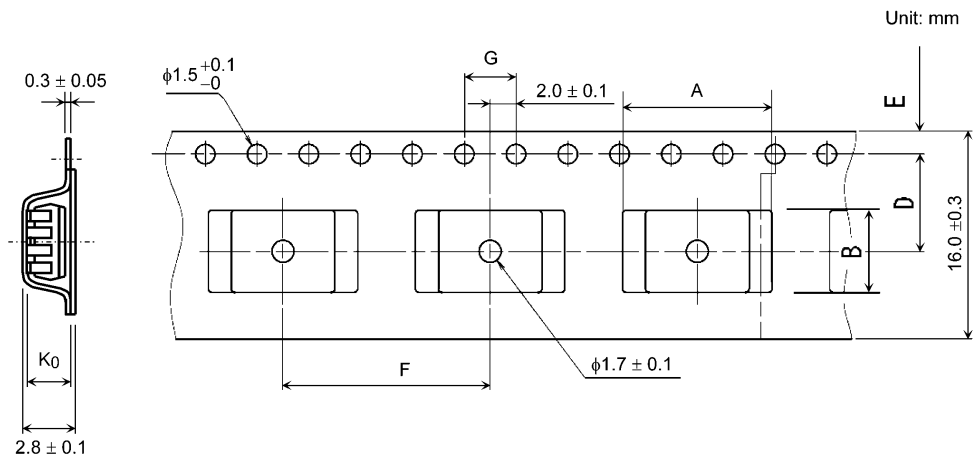


Table Tape Dimensions (unit: mm, tolerance: ±0.1)

Symbol	Dimension	Remark
A	11.55	—
B	6.35	—
D	7.5	Center line of embossed cavity and sprocket hole
E	1.75	Distance between tape edge and sprocket hole center
F	16.0	Cumulative error +0.1/-0.3 (max) per 10 empty cavities holes
G	4.0	Cumulative error +0.1/-0.3 (max) per 10 sprocket holes
K ₀	2.4	Internal space

17.3.5. Reel Specification

Material: Plastic

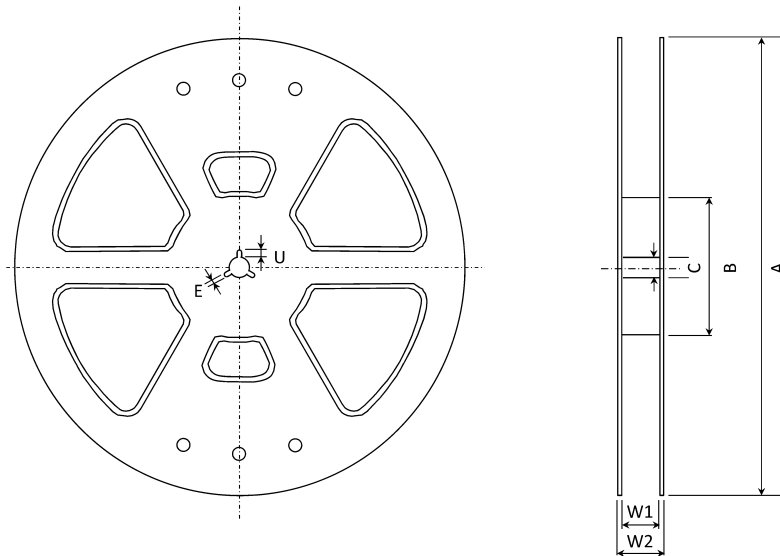
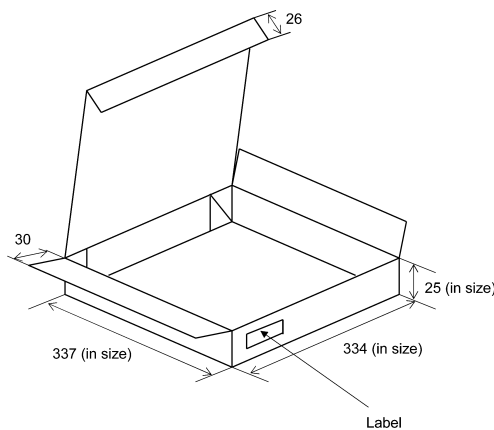


Table Reel Dimensions (unit: mm)

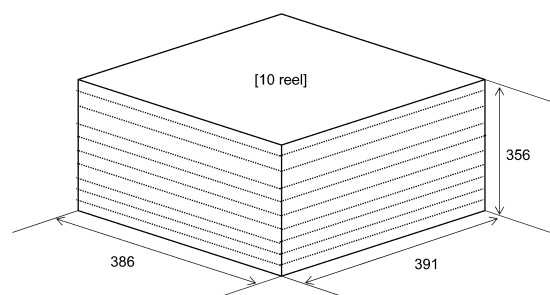
Symbol	Dimension
A	$\phi 330 \pm 2$
B	$\phi 100 \pm 1$
C	$\phi 13 \pm 0.5$
E	2.0 ± 0.5
U	4.0 ± 0.5
W1	17.4 ± 1.0
W2	21.4 ± 1.0

17.4. Packing (Note)

Either one reel or ten reels of photocouplers are packed in a shipping carton.



1 reel/carton (unit: mm)



10 reel/carton (unit: mm)

Note: Taping reel diameter: $\phi 330$ mm

17.5. Label Format

- (1) Carton: The label provides the part number, quantity, lot number, the Toshiba logo, etc.
- (2) Reel: The label provides the part number, the taping name, quantity, lot number, etc.

17.6. Ordering Information

When placing an order, please specify the part number, tape type and quantity as shown in the following example.

Example) TLP7830(TL,E(O 1500 pcs

Part number: TLP7830

Tape type: TL

[[G]]/RoHS COMPATIBLE: E (**Note1**)

Domestic ID (Country / Region of origin: Japan): O

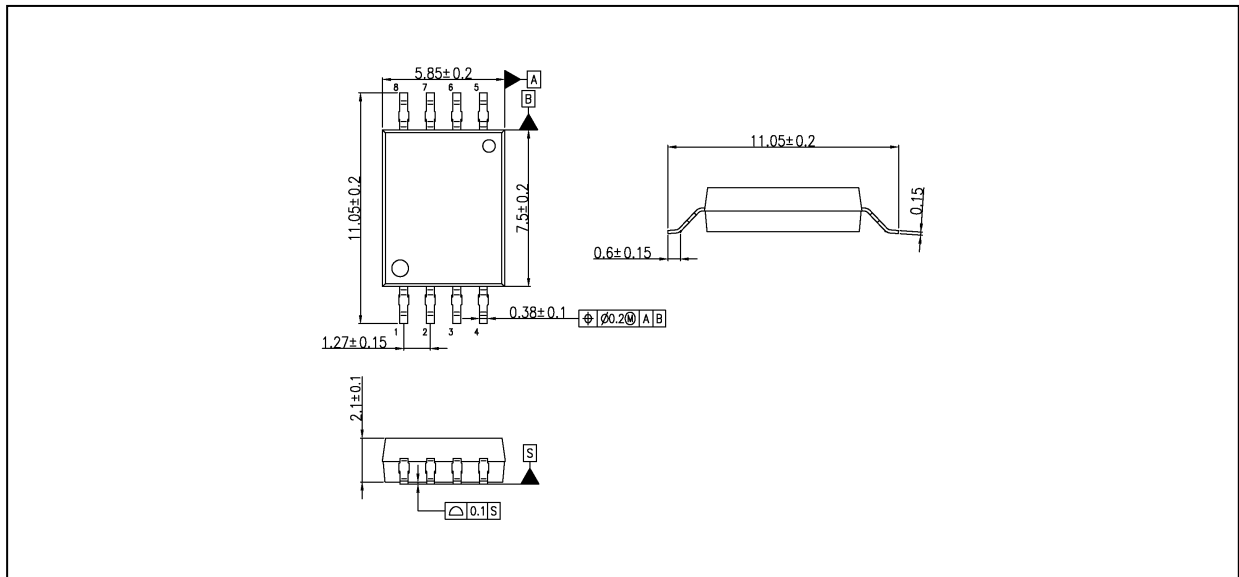
Quantity (must be a multiple of 1500): 1500 pcs

Note1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

Package Dimensions

Unit: mm



Weight: 0.205 g (typ.)

Package Name(s)
TOSHIBA: 11-6B1A

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